Overview

HP EliteBook 1040 14" G9 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Ambient Light Sensor (Optional)
- 3. Webcam
- 4. Camera Shutter
- 5 IR Camera (Optional)
- 6. IR Camera LEDs (Optional)
- 7. Glass Clickpad
- 1. SuperSpeed USB 20Gbps is not available with ThunderboltTM 4.

- 8. Smartcard Reader (Optional)
- 9. LED Indicator
- **10.** ThunderboltTM 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPortTM 1.4)¹
- **11.** ThunderboltTM 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPortTM 1.4)¹
- **12.** SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)
- 13. HDMI 2.0b Port (Cable not included)

Overview



Right

- 1. Power Button Key
- 2. Audio Combo Jack
- **3.** SuperSpeed USB Type-A 5Gbps signaling rate (Charging) **6.** (USB 3.2 Gen 1)
- 4. Nano Security Lock Slot (Lock sold separately)
- 5. SIM Card Slot (Optional)

Touch Fingerprint Sensor (Select models)

Overview

At a Glance

- Preinstalled with Windows 11 versions or FreeDOS
- A new clamshell ultraslim design with precision-crafted magnesium chassis for a premium look and feel
- 12th Generation Intel® Core™ i5, i7 U series, up to ten-core
- New 16:10 aspect ratio screen reduces the need to scroll by showing more vertical content than 16:9
- New 5MP camera with HP Auto Frame allows you around a little without losing viewers' attention during video calls
- New DDR5 memory (up to 64GB) and PCI Gen4 SSDs provide fast access to your work.
- Choice of displays:

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 250 nits, 45% NTSC, non-touch

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 250 nits, 45% NTSC, touchscreen

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 400 nits, 100% sRGB, non-touch with HP Eye Ease

35.6 cm (14"?) diagonal AG WUXGA (1920x1200) LED-backlit, 1000 nits, 100% sRGB, HP Sure View Reflect, non-touch with HP Ey Ease

- Redesigned keyboard layout to include easy use of discrete PgUp/Dn, End, and Home keys
- Choose from 38Wh or 51Wh battery options
- HP Wolf Security for Business creates a hardware-enforced, always-on, resilient defense
- Larger clickpad surface for easier, more intuitive input
- Connectivity with optional Intel® 5000 5G/WWAN available world-wide, and Thunderbolt[™] Docking (Dock sold separately)
- Undergoes MIL-STD 810H tests
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles
- Designed to support all HP docking options including the HP Universal Dock G5

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP EliteBook 1040 14" G9 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 11 Pro ¹

Windows 11 Pro Education ¹

Windows 11 Home - HP recommends Windows 11 Pro for Business¹

Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business¹ Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement) ¹

Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions wi require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

PROCESSORS

Processor	Cores	Number	Number	Threads	L3 Cache	_	Turbo uency	_	se uency	Intel SIPP/vPro®
3,4,5,6,7	Cores	P-cores	E-cores	Tilleaus	Lacine	P- cores	E- cores	P- cores	E- cores	Enterprise
Intel® Core TM i7-	10	2	8	12	12MB	4.8	3.6	1.8	1.3	Х
1265U Intel® Core TM i7-	10	2	8	12	12MB	GHz 4.7	GHz 3.5	GHz 1.7	GHz 1.2	
1255U						GHz	GHz	GHz	GHz	
Intel® Core TM i5-	10	2	8	12	12MB	4.4	3.3	1.2	1.2	X
1245U						GHz	GHz	GHz	GHz	
Intel® Core TM i5-	10	2	8	12	12MB	4.4	3.3	1.3	0.9	
1235U						GHz	GHz	GHz	GHz	

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on produconfigured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
- 7. Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired

Technical Specifications

LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® X? Graphics 8

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.3 9

8. Intel® Iris® X? Graphics capabilities require system to be configured with Intel® CoreTM i5 or i7 processors and dual channel memory. Intel® Iris® X? Graphics with Intel® CoreTM i5 or 7 processors and single channel memory will only function as UHD graphics.

9. HDMI cable sold separately

DISPLAY

Non-Touch

35.6 cm (14") diagonal, WUXGA bent, anti-glare UWVA, 250 nits, 45%NTSC, time of flight sensor, with 5 MP+IR camera (1920 x 1200) 10,11

35.6 cm (14") diagonal, WUXGA bent, anti-glare UWVA, 250 nits, 45%NTSC, time of flight sensor, with 5 MP+IR camera for WWAN (1920 x 1200) 10,11

35.56 cm (14") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera (1920 x 1200) with HP Eye Ease 10,11

35.56 cm (14") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR Camera for WWAN (1920 x 1200) with HP Eve Ease 10,11

35.56 cm (14") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera (1920 x 1200) with HP Eye Ease 10,11,12,13

35.56 cm (14") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor, time of flight sensor, with 5MP+IR camera for WWAN (197 x 1200) with HP Eye Ease 10,11,12,13

Touch

35.6 cm (14") diagonal, WUXGA bent, anti-glare UWVA, 250 nits, 45%NTSC, with 5 MP+IR camera, time of flight sensor Touch on Panel (1920 x 1200) 10,11,13

35.6 cm (14") diagonal, WUXGA bent, anti-glare UWVA, 250 nits, 45%NTSC, with 5 MP+IR camera, time of flight sensor for WWAN Touch on Panel (1920 x 1200) 9,10,12

DisplayPortTM 1.2

HDMI 2.0 Support resolution up to 4K @60 Hz 9

Displays support

Supports dual display through the dock

Display Size (diagonal)

14

35.56 cm (14")

9. HDMI cable sold separately

Technical Specifications

- 10. HD content required to view HD images.
- 11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 12. HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 13. Actual brightness will be lower with touchscreen or HP Sure View.

DOCKING (Sold Separately)

Docking station model #1 HP Thunderbolt Dock G2
Docking station model #2 HP USB-C Dock G5

Docking station model #3 HP USB-C/A Universal Dock G2

For additional aftermarket options and docking specs please see page 41.

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCIe® Gen4x4 NVMeTM M.2 SSD TLC ¹⁴
1 TB PCIe® Gen4x4 NVMeTM M.2 SSD TLC ¹⁴
512 GB PCIe® Gen4x4 NVMeTM M.2 SSD TLC ¹⁴
512 GB PCIe® Gen4x4 NVMeTM SED TLC OPAL2 ¹⁴
512 GB PCIe® NVMeTM Value M.2 SSD ¹⁴
256 GB PCIe® Gen4x4 NVMeTM M.2 SSD TLC ¹⁴
256 GB PCIe® Gen4x4 NVMeTM SED TLC OPAL2 ¹⁴
256 GB PCIe® NVMeTM Value M.2 SSD ¹⁴

14. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 an 11) is reserved for system recovery software.

MEMORY

Technical Specifications

Maximum Memory

64GB DDR5-4800 15

Memory

64GB DDR5-4800 (2x32GB) ¹⁵ 32GB DDR5-4800 (2x16GB) ¹⁵ 32GB DDR5-4800 (1x32GB) ¹⁵ 16GB DDR5-4800 (2x8GB) ¹⁵ 16GB DDR5-4800 (1x16GB) ¹⁵ 8GB DDR5-4800 (1x8GB) ¹⁵

Memory Slots

2 SODIMM DDR5 SODIMMS, system runs at 4800 Supports Dual Channel Memory

15. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensurcompatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WI AN

Intel® AX211 Wi-Fi6E + Bluetooth® 5.2 M.2 160MHz CNVi Word-Wide WLAN vPro ^{16,17,18} Intel® AX211 Wi-Fi6E + Bluetooth® 5.2 M.2 160MHz CNVi Word-Wide WLAN non-vPro ^{16,18}

WWAN

Intel® 5000 5G Solution WWAN ^{19,20}
Intel® XMM 7560 R+ LTE-Advanced Pro WWAN (Cat 16) ¹⁹

NFC

Near Field Communications Controller ²¹
HP Module with NXP NFC Controller NPC300 I2C NCI

Miracast

Native Miracast Support 22

16. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

17. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

18. For full Intel® vProTM functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platforn general html

19. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, networ conditions, and other factors. 4G LTE not available on all products, in all regions.

20. Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

21. Sold separately or as an optional feature.

22. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



Technical Specifications

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Discrete Amplifiers Integrated dual array microphone

Speaker Power

2W/4ohm Per speaker

Camera

5 MP+IR camera 21

Sensors

ALS (ambient light sensor) Magnetometer Hall Sensor Gyro Accelerometer HP Tamper Lock ²³

- 21. Sold separately or as an optional feature.
- 23. HP Tamper Lock must be enabled by the customer or your administrator.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Kevboard

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

ESC: system information

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center

home

end

Power Button (with LED)

Delete

Hidden Function Keys

Technical Specifications

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Software

HP Quick Touch
HP Quick Drop ²⁴
HP Easy Clean²⁵
HP PC Hardware Diagnostics Windows
myHP
Tile App ²⁶
HP Smart Support ²⁷
HP Connection Optimizer
HP Hotkey Support
HP Support Assistant ²⁸

HP Notifications
HP Privacy Settings

IIP Dower Manager

HP Power Manager

Buy Microsoft Office (Sold separately)

Manageability Features

HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download) ²⁹ HP Client Management Script Library (download) HP Driver Packs (download) HP Cloud Recovery ³⁰ HP Client Catalog (download)

Security Management HP Wolf Security of Business ³¹ includes:

HP Sure Click ³²
HP Sure Sense ³³
HP Sure Run Gen5 ³⁴
HP Sure Recover Gen5 ³⁵
HP Sure Start Gen7 ³⁶
HP Tamper Lock
HP Sure Admin ³⁷

HP Client Security Manager Gen7 38

BIOS

HP BIOSphere Gen6 ³⁹
HP Secure Erase ⁴⁰
Absolute Persistence Module ⁴¹
HP DriveLock & Automatic DriveLock
BIOS Update via Network
HP Wake on WLAN
HP Fingerprint Sensor ⁴²
Secured-Core PC Enable ⁴³
TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

Security TPM

Technical Specifications

Model: Infineon SLB9672VU2.0

Version: 15.21 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Support

Yes

FirstNet Certified

Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes

UEFI version: 2.7 Class: Class 3

24. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Androic device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

25. HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are no disabled. See user guide for cleaning instructions.

26. Some Tile features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. Tile will function as long as the PC has battery power.

27. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or i can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

28. HP Support Assistance requires Windows and Internet Access.

29. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

30. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoic loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

31. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement..

32. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.

33. HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS.

34. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.

35. HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

36. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher.

37. HP Sure Admin requires Windows 10 or higher, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

38. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.

39. HP BIOSphere Gen6 features may vary depending on the platform and configuration.

40. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® OptaneTM.

41. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, che with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.

42. HP Fingerprint sensor is an optional feature that must be configured at purchase.

43. Secured-Core PC Enable requires an Intel® vPro®, AMD RyzenTM Pro processor or Qualcomm® processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC is enabled from the factory.

Technical Specifications

POWER

Power Supply

HP Smart 65 W USB Type-C adapter ⁴⁴ HP Smart 65 W Slim USB Type-C adapter ⁴⁴ HP Smart 45 W USB Type-C adapter ⁴⁴

Battery

HP Long Life 3-cell, 38 Wh Polymer ^{45,46} HP Long Life 3-cell, 51 Wh Polymer ^{45,46} Compliant with UL 1642 Standard

Power Cord

3-wire plug - 1m 2-wire plug - 1m

Battery Life

Up to 13 hours 45 minutes (51 Whr battery) ⁴⁷ Up to 10 hours (38 Whr battery) ⁴⁷

- 44. Availability may vary by country.
- 45. Battery is internal and not replaceable by customer. Serviceable by warranty.

46. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
47. MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight- 38 Whr ⁴⁸

Starting at 2.56 lb Starting at 1.16 kg

Product Dimensions (W x D x H)

12.41 x 8.83 x 0.76 in 31.52 x 22.431 x 1.931 cm

48. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Technical Specifications

- 2 ThunderboltTM 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPortTM 1.4) ⁴⁹
- 2 Super Speed USB Type-A 5Gbps signaling rate (1 charging) (USB 3.2 Gen 1)
- 1 HDMI 2.0 9
- 1 Headphone/microphone combo jack
- 1 Nano Security Lock Slot (Lock sold separately)
- 1 Smartcard reader (Optional)
- 1 nano SIM card slot
- 9. HDMI cable sold separately
- 49. SuperSpeed USB 20Gbps is not available with ThunderboltTM 4.

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

50. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

SYSTEM UNIT

Stand-Alone Power Requirements Type-C Adapter

(AC Power)

Nominal Operating Voltage AC 20V

Average Operating Power

Integrated graphics Yes
Discrete Graphics N/A

Max Operating Power UMA<65W

Temperature

Operating 32° to 95° F (0° to 35° C)

Non-operating 41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Technical Specifications

Operating 0.75 grams Non-operating 1.50 grams

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m) Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard

Certifications

Regulatory Model Number HSN-I45C-4

UL Yes
CSA Yes
FCC Compliance Yes
ENERGY STAR® Certified⁵¹

EPEAT® Gold in the United States⁵²

ICES Yes Australia / Yes NZ A-Tick Compliance Yes CCC Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes **GOST** Yes Saudi Arabian Compliance (ICCP) Yes **SABS** Yes

- 51. Configurations of the HP EliteBook 1040 14" G9 Notebook PC that are ENERGY STAR® qualified are identified as HP EliteBook 1040 14" G9 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.
- 52. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

Technical Specifications

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC NB2X 250 eDP 1.2 w/o PSR 45 bent LCD Panel

 Outline Dimensions (W x H x D)
 307.590 x 199.550 (max)

 Active Area
 301.590 X 188.500 (typ)

Weight 300 (max)
Diagonal Size 14

Thickness 3.0 / 5.0 (max)

Interface eDP 1.2
Surface Treatment Anti-Glare
Touch Enabled No

Contrast Ratio1000:1(typ)Refresh Rate60 HzBrightness250 nits

Pixel Resolution - Format 1920 x 1200 (WUXGA)

BacklightWLEDPixel ResolutionRGBColor Gamut CoverageNTSC 45%Color Depth8 bits

Viewing Angle UWVA 89/89/89

Low Blue Light No

Power Consumption (W, EBL@ 2.20 (max) / 2.70 (max) 150nits max/ 200nits max)

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC NB2X 250 TOP eDP 1.2 w/o PSR 45 bent LCD Panel

 Outline Dimensions (W x H x D)
 307.590 x 199.550 (max)

 Active Area
 301.590 x 188.500 (typ)

Weight 300 (max)

Diagonal Size 14

Thickness 3.0 / 5.0 (max)
Interface eDP 1.2
Surface Treatment Anti-Glare
Touch Enabled Yes¹
Contrast Ratio 1000:1(typ)

Refresh Rate 60 Hz **Brightness** 250 nits¹

Pixel Resolution - Format 1920 x 1200 (WUXGA)

BacklightWLEDPixel ResolutionRGBColor Gamut CoverageNTSC 45%Color Depth8 bits

Viewing Angle UWVA 89/89/89

Low Blue Light No.

Power Consumption (W, EBL@ 2.10 (max) / 2.60 (max) 150nits max/ 200nits max)

Technical Specifications

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2X 400 eDP 1.4+PSR2 Low-Power 100 bent LCD Panel

 Outline Dimensions (W x H x D)
 307.590 x 199.550 (max)

 Active Area
 301.590 X 188.500 (typ)

Weight 210 (max)
Diagonal Size 14

Thickness 2.0 / 3.8 (max)

Interface eDP 1.4
Surface Treatment Anti-Glare
Touch Enabled No

Contrast Ratio1000:1(typ)Refresh Rate60 HzBrightness400 nits

Pixel Resolution - Format 1920 x 1200 (WUXGA)

BacklightWLEDPixel ResolutionRGBColor Gamut CoveragesRGB 100%Color Depth8 bits

Viewing Angle UWVA 89/89/89

Low Blue Light Yes

Power Consumption (W, EBL@ 1.29 (max) / 1.66 (max) 150nits max/ 200nits max)

14.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2Y 1000 eDP 1.3+PSR 100 PrivacyG4 Plus bent LCD Panel

 Outline Dimensions (W x H x D)
 307.600 x 199.550 (typ)

 Active Area
 301.680 x 188.500 (typ)

Weight 238 (max)

Diagonal Size 14

Thickness 2.2 / 3.9 (max)
Interface eDP 1.3
Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio1500:1(typ)Refresh Rate60 HzBrightness1000 nits

Pixel Resolution - Format 1920 x 1200 (WUXGA)

BacklightWLEDPixel ResolutionRGBColor Gamut CoveragesRGB 100%Color Depth8 bits

Viewing Angle UWVA 85/85/85

Low Blue Light Yes

Power Consumption (W, EBL@ N/A
150nits max/ 200nits max)

Technical Specifications

STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

SSD 256GB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 256GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 4000 MB/s ±20%

 Maximum Sequential Write
 2000 MB/s ±20%

 Logical Blocks
 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

SSD 512GB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 6400 MB/s ±20%

 Maximum Sequential Write
 3500 MB/s ±20%

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 1TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 6400 MB/s ±20%

 Maximum Sequential Write
 5000 MB/s ±20%

 Logical Blocks
 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Technical Specifications

SSD 2TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 2TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 6400 MB/s ±20%

 Maximum Sequential Write
 5000 MB/s ±20%

 Logical Blocks
 4,000,797,360

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

256GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive

Form Factor M.2 2280
Capacity 256GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 4000 MB/s ±20%

 Maximum Sequential Write
 2000 MB/s ±20%

 Logical Blocks
 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TCG Opal 2.0; TRIM; L1.2

512GB PCIe-4x4 2280 NVME Form Fact
Self Encrypted OPAL2 Three
Layer Cell Solid State Drive
LAND To

Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

 Maximum Sequential Read
 6400 MB/s ±20%

 Maximum Sequential Write
 3500 MB/s ±20%

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TCG Opal 2.0; TRIM; L1.2

Technical Specifications

SSD 256GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 1500 MB/s ±20%

 Maximum Sequential Write
 750 MB/s ±20%

 Logical Blocks
 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

SSD 512GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 1500 MB/s ±20%

 Maximum Sequential Write
 750 MB/s ±20%

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

NETWORKING/COMMUNICATIONS

Intel® AX211 Wi-Fi 6E + Wireless LAN Standards IEEE 802.11a
Bluetooth® 5.2 M.2 IEEE 802.11b
160MHz CNVi World-Wide IEEE 802.11g
WLAN vPro®1,5 IEEE 802.11n

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11r

Interoperability Wi-Fi certified

Frequency Band
● 802.11b/g/n/ax 2.402 - 2.482 GHz

Technical Specifications

802.11a/n/ac/ax

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 5.955 - 6.415 GHz

6.435 - 6.515 GHz 6.535 - 6.875 GHz 6.895 - 7.115 GHz

● 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: max 300Mbps802.11ac: 1733Mbps802.11ax: max 2.4Gbps

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security² IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification WPA3 certification IEEE 802.11i WAPI

WAI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power³ 802.11b: +17dBm minimum

802.11g: +16dBm minimum 802.11a: +17dBm minimum

802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +13dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT160(5GHz): +10dBm minimum 802.11ax HE40(2.4GHz): +12dBm minimum 802.11ax HE80(5GHz): +10dBm minimum 802.11ax HE160(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum

802.11ac, MCS0(VHT80): -84dBm maximum

Technical Specifications

802.11ac, MCS9(VHT80): -59dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

Weight 1. Type 2230: 2.8g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1/5.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy : 0~79 (1 MHz/CH)
Channels BLE : 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management Certifications

ETS 300 328, ETS 300 826

Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance

Supported LE Link Layer Ping LE Dual Mode

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Technical Specifications

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance

LE Advertisement Extensions

Channel Selection Algo

Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE

LE Long Range

- 1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Require a wireless router, sold separately, that supports 80MHz and higher channels.

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.2 M.2 160MHz CNVi World-Wide WLAN non-vPro®1,5 **Wireless LAN Standards**

IEEE 802.11a

IEEE 802.11b

IEEE 802.11g

IEEE 802.11n IEEE 802.11ac

IEEE 802.11ax

IEEE 802.11d

IEEE 802.110

IEEE 802.11e IEEE 802.11h

IEEE 802.11i

IEEE 802.11k

IEEE 802.11r

IEEE 802.11v

Interoperability

Wi-Fi certified

Frequency Band

802.11b/g/n/ax

2.402 - 2.482 GHz

802.11a/n/ac/ax

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz

5.25 - 5.35 GHz

5.47 - 5.725 GHz

5.825 - 5.850 GHz

5.955 - 6.415 GHz

6.435 - 6.515 GHz

6.535 - 6.875 GHz

Technical Specifications

6.895 - 7.115 GHz

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: max 300Mbps802.11ac: 1733Mbps802.11ax: max 2.4Gbps

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security² IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification WPA3 certification IEEE 802.11i WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power³ 802.11b: +17dBm minimum 802.11g: +16dBm minimum

802.11a: +17dBm minimum

802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +13dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum 802.11ac VHT160(5GHz): +10dBm minimum 802.11ax HE40(2.4GHz): +12dBm minimum 802.11ax HE80(5GHz): +10dBm minimum 802.11ax HE160(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0(VHT80): -84dBm maxim

802.11ac, MCS0(VHT80): -84dBm maximum 802.11ac, MCS9(VHT80): -59dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Technical Specifications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8q 2. Type 1216: 1.3q

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

> -40° to 176° F (-40° to 80° C) Non-operating

Humidity Operating 10% to 90% (non-condensing)

> Non-operating 5% to 95% (non-condensing)

Altitude 0 to 10,000 ft (3,048 m) Operating

0 to 50,000 ft (15,240 m) Non-operating

LED Activity LED Amber - Radio OFF; LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1/5.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

Data Rates and Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps **Throughput**

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported

Microsoft Windows Bluetooth Software

Link Topology

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328, ETS 300 826 **Power Management**

Low Voltage Directive IEC950

UL, CSA, and CE Mark Certifications

Bluetooth Profiles

BT4.1-ESR 5/6/7 Compliance Supported LE Link Layer Ping

LE Dual Mode

LE Link Laver

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Technical Specifications

Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance **LE Advertisement Extensions** Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

- 1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.
- 2. Check latest software/driver release for updates on supported security features.
- 3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Require a wireless router, sold separately, that supports 80MHz and higher channels.

Intel(R) 5G Solution 5000¹

Technology/Operating bands

WCDMA/HSPA+ operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)

LTE FDD/TDD operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)

Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)

Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)

Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)

Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)

Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)

Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)

Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL)

Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)

Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)

Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)

Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)

Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

Band 29: 717 to 728 MHz (DL)

Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)

Band 32: 1452 to 1496 MHz (DL)

Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL)

Band 39: 1880 to 1920 MHz (UL/DL)

Band 40: 2300 to 2400 MHz (UL/DL)

Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL)

Band 43: 3400 to 3800 MHZ (UL/DL)

Band 46: 5150 to 5925 MHZ (DL)

Technical Specifications

Band 48: 3550 to 3700 MHZ (UL/DL)

Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

5GNR Sub 6GHZ

n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

n38: 2570 to 2620 MHz (UL/DL) n40: 2300 to 2400 MHz (UL/DL) n41: 2496 to 2690 MHz (UL/DL) n48: 3550 to 3700 MHZ (UL/DL)

n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)

Wireless protocol standards

5GNR Air Interface 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput - 4 × 4 MIMO across 5x

200 Mbps/uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA R99.

3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands GPS: L1 (1575.42MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)

Maximum data rates SA 5G/NR sub-6 Peak: DL4.67Gbps/ UL 1.25Gbps

> 5G NSA sub 6G: DL: 3.8 Gbps/UL 700Mbps LTE: ue-CategoryDL 19, (DL: 1.6 Gbps) ue-CategoryUL 13, (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 11.5 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

NR: 23 dBm in all band except n41, n77, n78 and n79

LTE n41, n77, n78 and n79 HPUE = 26dBm

HSPA+: 23.5 dBm

Maximum power consumption 5G Sub 6: 2500 mA

> LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Kev B

Weight 8 q

Dimensions 52 mm × 30 mm × 2.6 mm

(Length x Width x Thickness)

Technical Specifications

1. Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 51 module planned to be available in select platforms and select countries, where carrier supported.

Intel® XMMTM 7560 R+ LTE-Advanced Pro¹ Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower),

850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66), 600 (band 71).

TDD LTE: 2100 (Band 34), 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 3700 (Band 43), 3700 (band 48), 5200

(Band 46 RX only) MHz;

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards 3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput

up to 978Mbps; UL-CAT.13 40MHz throughput up to 150Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098

 MHz

Maximum data rates LTE: 978 Mbps (Download), 150 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

HSPA+: 23.5 dBm

Maximum power LTE: 1,200 mA (peak); 900 mA (average) consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 q

Dimensions 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

eSIM Support

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available ir all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications

Near Field Communications Controller (optional) Dimensions (L x W x H)

Module 25 mm by 10 mm by 2.0 mm

Chipset

NPC100

System interface

120

NFC RF standards

ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 13093

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)

Mode (1)

ISO/IEC 14443 A ISO/IEC 14443 B

ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-

VICC) Mode (1)

ISO/IEC 14443 A ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency

13.56 MHz

0°C to 70°C

NFC Modes Supported
Raw RF Data Rates

Reader/Writer, Peer-to-Peer 106, 212, 424, 848 kbps

Operating temperature
Storage temperature

-20°C to 125°C

Humidity

10-90% operating 5-95% non-operating

Supply Operating voltage 4.35 to 5.25 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption

(Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)

Mode Power Consumption, Typical

Polling 7.3 mA

Detected Test Tag Type 1 Total 283.8 mA

Net Module 236.8 mA

Detected Test Tag Type 2 Total 288.8 mA

Net Module 241.8 mA

Detected Test Tag Type 3 Total 287.7 mA

Net Module 240.7 mA

Detected Test Tag Type 4 Total 282.3 mA

Net Module 235.3 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.

POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time. usage. environment. temperature. system configuration. loaded apps. features. power management settings and other factors

Technical Specifications

AC Adapter 45 Watt nPFC Standard USB type C Straight 1.8m Dimensions (H x W x D)

Weight Input

Output

94.0mm x 40.0mm x 26.5mm

192.5g +/-10%

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%

Input frequency range 47 ~ 63Hz

Input AC current Max. 1.4 A at 90 Vac

Output power 5V/15W

9V/27W 12V/36W 15V/45W

DC output 5V/9V/12V/15V **Hold-up time** 5ms at 115 Vac input

Output current limit <5.0A

Connector C6

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1

and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

Technical Specifications

AC Adapter 65 Watt nPFC Slim USB type C Straight 1.8m **Dimensions (H x W x D)** 88x53.5x21mm **Weight** unit: 220q +/- 10q

Input Efficiency

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A

88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65W

DC output 5V/9V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

Connector C6

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity5% to 95%Storage Humidity5% to 95%

EMI and Safety

Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1

and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Standard USB type C Straight 1.8m Dimensions (H x W x D)

Weight

Input

Output

90.0mm x 51.0mm x 28.5mm

250g +/-10%

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V: 81.5% 9V: 86.7% 12V: 88% 15V: 88% 20V: 89%

Input frequency range 47 ~ 63Hz

Input AC current Max. 1.6 A at 90 Vac

Output power 5V/15W

9V/27W 12V/60W 15V/60W 20V/65W

DC output 5V/9V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

Connector C6

Technical Specifications

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety

*CE Mark - full compliance with LVD and EMC directives Certifications

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1

and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B. CISPR32 Class B. CCC. NOM-001 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

HP 3-cell Long Life Li-Ion (38Wh)1

Dimensions (H x W x D)

251.8 x 66.1 x 6.82mm (9.91 x 2.6 x 0.27 inch)

Weight 0.184kg +/- 10g(0.406lb)

Cells/Type 3cell Lithium-Ion Polymer cell / 564975 11.58V Energy **Voltage**

> **Amp-hour capacity** 3.283Ah Watt-hour capacity¹ 38Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

> Operating (Discharging) 14° to 140° F (-10° to 60° C)

Fuel Gauge LED

Follow product spec Warranty

Optional Travel Battery No

Available

HP 3-cell Long Life Li-Ion

(51 Wh) 1

Dimensions (H x W x D)

Temperature

251.8 x 70.3 x 6.82mm (9.91 x 2.77 x 0.27 inch)

Weight 0.229kg +/- 10g (0.505 lb)

Cells/Type 3cell Lithium-Ion Polymer cell / 566075

Energy Voltage 11.58V

> Amp-hour capacity 4.431Ah

Watt-hour capacity¹ 51.3Wh

> Operating (Discharging) 14° to 140° F (-10° to 60° C)

> > No

32° to 113° F (0° to 45° C)

Fuel Gauge LED

Follow product spec Warranty

Optional Travel Battery

Available

Operating (Charging)

AUDIO

Technical Specifications

HD Stereo Codec Realtek ALC3315

Audio I/O Ports Headset: CTIA only and Headphone-out

Internal Speaker Amplifier Cirrus Logic High-Efficiency Boosted Class D Amplifier

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow

independent audio. Following MSFT Behaviour

Support 3.5mm Headset: CTIA only and Headphone-out

DAC: 44.1k/48kHz

ADC: 48kHz

Wavetable Syntheses

Sampling

Analog Audio

of Channels on Line-Out

Internal Speaker Yes

FINGERPRINT READER

Sensor vendor Synaptics FS7604

Sensor type Capacitive DPI resolution 363DPI

Scan area 7.4x6mm sensor area

False Rejection Rate <1%

False Acceptance Rate 1:50K FAR
Mobile Voltage Operation 3.0V to 3.6V
Operating Temperature 0~60°C
Current Consumption Image 100mA Max

Current Consumption Image 100mA Low Latency Wait For Finger 260 uA

Capture Rate <30msec per image

ESD Resistance IEC 61000-4-2 4B (+/-15KV)

Detection Matrix 363 dpi / 7.4x6mm sensor area

ENVIRONMENTAL DATA

Specifications

ENVIRUNMENTAL DATA	
Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT? Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*
Sustainable Impact	Ocean-bound plastic in Speaker

Low halogenOutside Box and c

 Outside Box and corrugated cushions are 100% sustainably sourced and recyclable

Molded Paper Pulp Cushion inside box is 100% sustainably sourced and

• 60% post-consumer recycled plastic

Technical Specifications

	recyclable	voilable			
System Configuration	Bulk packaging av The configuration used for Notebook model is based or	the Energy Consumption a	nd Declared Noise Emissions data for the otebook"?.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Sort idle)	5.88 W	6.17 W	5.92 W		
Normal Operation (Long		••••			
idle)	1.66 W	1.85 W	1.76 W		
Sleep	1.66 W	1.85 W	1.76 W		
Off	0.46 W	0.48 W	0.41 W		
	does not offer ENERGY STAI typically configured PC feat Windows® operating syster	R® compliant configuration curing a hard disk drive, a h m.	Specifications for computers. If a model factorise, then energy efficiency data listed is for a lighter efficiency power supply, and a Microsoft		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short dle)	20.1 BTU/hr	21.1 BTU/hr	20.2 BTU/hr		
Normal Operation (Long	20.1 510/11	21.1 010/111	20.2 51 0/111		
dle)	5.7 BTU/hr	6.3 BTU/hr	6 BTU/hr		
Sleep	5.7 BTU/hr	6.3 BTU/hr	6 BTU/hr		
Off	1.6 BTU/hr	1.6 BTU/hr	1.4 BTU/hr		
	*NOTE: Heat dissipation is contact attained for one hour.	alculated based on the mea	asured watts, assuming the service level is		
Declared Noise Emissions	Sound Power		Sound Pressure		
(in accordance with	(L _{WAd} , bels)		(L _{pAm} , decibels)		
ISO 7779 and ISO 9296)	- William		· pmii		
Typically Configured - Idle	2.9		21.6		
Fixed Disk - Random writes	3.6		28.5		
Optical Drive - Sequential	4.1		33.2		
reads Longevity and Upgrading	This product can be upgra Upgradeable features and		ts useful life by several years.		
Additional Information	 Spare parts are available throughout the warranty period and or for up to "5"? years after the end of production. This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net 				

Technical Specifications

	 Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product is 95.4% recycle-able when properly disposed of at end of life. 					
Packaging Materials	External:	PAPER/Corrugated	269 g			
		PAPER/Paper	3 g			
		PAPER/Molded Pulp	108 g			
	Internal:	PLASTIC/Polyethylene low density - LDPE	13 g			
	The plastic	packaging material contains at least 0.0% recy	cled content.			
		ated paper packaging materials contains at leas				
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.					
Material Usage	the HP General http://www.gen_specific Asbes Certai Certai Cadmi Chlori Chlori Bis(2- Benzy	n Azo Colorants n Brominated Flame Retardants - may not be used ium nated Hydrocarbons nated Paraffins Ethylhexyl) phthalate (DEHP) l butyl phthalate (BBP)	pplychain/			
	 Diisob Forma Halogo Lead o Mercu Nickel carrieo Ozone Polybo Polybo Polybo 	of phthalate (DBP) utyl phthalate (DIBP) uldehyde enated Diphenyl Methanes carbonates and sulfates and Lead compounds ric Oxide Batteries - finishes must not be used on the external surface d by the user. Depleting Substances cominated Biphenyls (PBBs) cominated Biphenyl Ethers (PBBEs)	e designed to be frequently handled o			

voluntarily removed from most applications.

Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been

Polychlorinated Biphenyl (PCB)
Polychlorinated Terphenyls (PCT)

Technical Specifications	
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate	For more information about HP's commitment to the environment:
Environmental Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
footnotes	 http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf Percentage of ocean-bound plastic contained in each component varies by product
- Sociotes	 Recycled plastic content percentage is based on the definition set in the IEEE 1680.1- 2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded.
	 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	Fiber cushions made from 100% recycled wood fiber and organic materials.

COUNTRY OF ORIGIN

China

Options and Accessories (Sold separately and availability may vary by country)

DOCKING (Sold Separately)

Docking station model #1

Total number of supported displays

(incl.the notebook display)

ct.the notebook display)

Max.resolutions supported Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported

4

Single 8K@ 30Hz (multiple tiles) for Thunderbolt hosts

Non-TBT hosts DP 1.4 in high res mode (1) 8K video single cable@30Hz [10]

Dock Connectors 2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode

Technical limitationsThunderbolt Hosts:

Maximum of (4) displays with maximum resolution of 5K@ 30Hz running

Thunderbolt host.

Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or

running a non-Thunderbolt host in High Resolution mode @30Hz

Non-Thunderbolt hosts:

HP Thunderbolt Dock G2

The highest resolution for dual displays running a non-Thunderbolt host in multi-

function mode is

(1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port

Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1)

4K UHD @ 30Hz.

Docking station model #2

Total number of supported displays

(incl.the notebook display)

Max.resolutions supported

Dock Connectors

HP USB-C Dock G5

Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode) [10]

1xHDMI, 2xDP

Technical limitations Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution

mode.

3

Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K

UHD@ 30 Hz on HDMI in multi-function mode

The highest resolution for a non-Thunderbolt host in Multi-function mode is a

single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.

Docking station model #3

Total number of supported displays (incl.the notebook display)

Max.resolutions supported

Dock Connectors

HP USB-C/A Universal Dock G2

3

Triple 4K UHD@ 60Hz [10]

1xHDMI. 2xDP

Technical limitationsThe best resolution for dual or triple displays is 4K UHD@ 60Hz.

For use with the USB-A adapter that comes in the box the maximum number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the

host

Туре	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Executive Slim 14.1 Top Load	6KD04AA
	HP Prelude G2 15.6 Backpack	1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7AA

Options and Accessories	(Sold separatel	v and availability	v mav var	v bv country))
options and necessories	(Sola Separatel	y arra avaitability	,a, va.	y by country,	,

	HP Prelude Pro Recycled 15.6 Backpack	1X644AA
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA
	HP Renew 14 Laptop Sleeve	2E6U9AA,2E6V0AA
	HP Renew Business 14.1 Laptop Bag	3E5F9AA
	HP Renew Business 14.1 Laptop Sleeve HP Renew Business 17.3 Laptop Backpack	3E2U7AA 3E2U5AA
	HP Renew Business 17.3 Laptop Backpack HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 17.3 Laptop Bag HP Renew Business 15.6 Laptop Bag	3E5F8AA
	The Nethern Business 15.0 Euptop Bug	JESI ONIN
Docking	HP Thunderbolt 120W G2 Dock (Hook)	2UK37AA
	HP Thunderbolt 120W G2 Dock w/Audio (HOOK+MIXMASTER)	3YE87AA
	HP Thunderbolt 230W G2 Dock w/Combo Cable (Hook)	3TR87AA
	HP USB-C 120W G5 Dock (AdicoraA)	5TW10AA
	HP USB-C/A 120W G2 Universal Dock (Adicora-D)	5TW13AA
Hub	HP USB-C Mini Dock	1PM64AA
	HP Universal USB-C Multiport Hub	50H55AA
	HP USB-C Travel Dock G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB to Gigabit RJ45 Adapter	N7P47AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to VGA Adapter	N9K76AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gigabit RJ45 Adapter G2	4Z7Z7AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 125 USB-A Wired Mouse	265A9AA

Options and Accessories (Sold separately and availability may vary by country)

options and A	ccessories (Sold Separately and availability may vary by country)	
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1D0K8AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1D0K2AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
Power	HP 65W USB-C Auto Chevy AC Power Adapter	5TQ76AA
	HP 45W USB-C G2 Zeus AC Power Adapter	1HE07AA
	HP 45W USB-C LC Dali AC Power Adapter	1MZ01AA
	HP 65W USB-C Hades AC Power Adapter	1HE08AA
	HP 65W USB-C LC AC Power Adapter	1P3K6AA
	HP 65W USB-C Travel Slim Kermit AC Power Adapter	3PN48AA
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP SureKey Standard/Nano/Wedge Cable Lock	6UW42AA

Change Log

Date of change:	Version History:	Description of change:
	V1 to V2	

© Copyright 2022 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

Intel, Core and Intel vPro are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries. DisplayPortTM and the DisplayPortTM logo are trademarks owned by the Video Electronics Standards Association (VESA®) in the United States and other countries. USB Type-C® and USB-C® are trademarks of USB Implementers Forum. ENERGY STAR is a registered trademark of the U.S. Environmental Protection Agency. Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries.